

Product Information Sheet

MATERIAL ID:

EPO-TEK[®] OG133-8 (formerly 90-36-4)

Date: 12/2008

Per:

Rev: II

Material Description:

A single component, UV curable, thixotropic flexible epoxy adhesive/encapsulant designed for semiconductor and opto-electronic packaging. Glob top over IC and wire bonds, and low stress bonding of fiber optic components, are common applications. It is a replacement for EPO-TEK[®] OG133-5, and a non-flow version of EPO-TEK[®] OG133-7.

Number of Components:

Single

Mix Ratio by weight:

N/A

Cure Schedule (minimum)*

100mW/cm² for 2-3 minutes @ 320-500 nm (depending on thickness)

Specific Gravity:

1.13 --- Part A: Part B:

Pot Life:

N/A

Shelf Life:

One year at room temperature

NOTE: Container(s) should be kept closed in a dark location when not in use.

*Please see Applications Note(s) available on our website.

MATERIAL CHARACTERISTICS: *To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.*

* denotes test on lot acceptance basis; Cure condition: varies as required

PHYSICAL PROPERTIES:			
*Color (before cure):	Cloudy/Colorless	Die Shear @ 23°C:	3.2 Kg
*Consistency:	Slightly thixotropic paste	Degradation Temp:	353 °C
*Viscosity (23°C):		Weight Loss:	
@ 100 rpm	1000 - 1500 cPs	@ 200°C:	2.37 %
Thixotropic Index:	3.1	@ 250°C:	3.64 %
*Glass Transition	≤ 10 °C (Post-Cure)	@ 300°C:	5.72 %
	Dynamic Scan 20—200°C; Ramp -40—200°C @ 20°C/Min)	Operating Temp:	
Coefficient of Thermal Expansion (CTE):		Continuous:	- 55°C to + 150°C
Below Tg:	43 x 10 ⁻⁶ in/in°C	Intermittent:	- 55°C to + 250°C
Above Tg:	222 x 10 ⁻⁶ in/in°C	Storage Modulus @ 23°C:	< 1,000 psi
Shore A Hardness:	65	*Particle Size:	≤ 10 microns

OPTICAL PROPERTIES @ 23°C:	
Spectral Transmission:	> 90 % @ 640 nm > 95 % @ 900 nm
Index of Refraction:	1.5050 @ 589 nm